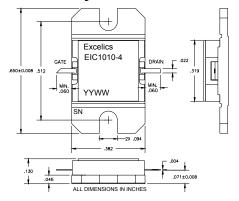


ISSUED 10/29/2008

10.0-10.70GHz 4-Watt Internally-Matched Power FET

FEATURES

- 10.0-10.70GHz Bandwidth
- Input/Output Impedance Matched to 50 Ohms
- +36.5 dBm Output Power at 1dB Compression
- 7.5 dB Power Gain at 1dB Compression
- 30% Power Added Efficiency
- -46 dBc IM3 at PO = 25.5 dBm SCL
- 100% Tested for DC, RF, and R_{TH}





Caution! ESD sensitive device.

ELECTRICAL CHARACTERISTICS (T_a = 25°C)

SYMBOL	PARAMETERS/TEST CONDITIONS ¹		TYP	MAX	UNITS
Freq	Frequency			10.7	Ghz
P _{1dB}	Output Power at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 1100mA	35.5	36.5		dBm
G _{1dB}	Gain at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 1100mA	6.5	7.5		dB
ΔG	Gain Flatness V _{DS} = 10 V, I _{DSQ} ≈ 1100mA			±0.6	dB
PAE	Power Added Efficiency at 1dB Compression V _{DS} = 10 V, I _{DSQ} ≈ 1100mA		30		%
ld₁ _{dB}	Drain Current at 1dB Compression		1200	1300	mA
IM3	Output 3rd Order Intermodulation Distortion Δf = 10 MHz 2-Tone Test; Pout = 25.5 dBm S.C.L ² V_{DS} = 10 V, $I_{DSQ} \approx 65\%$ IDSS		-46		dBc
I _{DSS}	Saturated Drain Current $V_{DS} = 3 \text{ V}, V_{GS} = 0 \text{ V}$		2000	2500	mA
V _P	Pinch-off Voltage $V_{DS} = 3 \text{ V}, I_{DS} = 20 \text{ mA}$		-2.5	-4.0	V
R _{TH}	Thermal Resistance ³		5.5	6.0	°C/W

Note: 1. Tested with 100 Ohm gate resistor.

ABSOLUTE MAXIMUM RATING FOR EFE

SYMBOLS	PARAMETERS	ABSOLUTE ¹	CONTINUOUS ²
Vds	Drain-Source Voltage	15V	10V
Vgs	Gate-Source Voltage	-5V	-4V
lgf	Forward Gate Current	48mA	14.4mA
lgr	Reverse Gate Current	-9.6mA	-2.4mA
Pin	Input Power	36dBm	@ 3dB Compression
Tch	Channel Temperature	175C	175C
Tstg	Storage Temperature	-65C to +175C	-65C to +175C
Pt	Total Power Dissipation	25W	25W

Note: 1. Exceeding any of the above ratings may result in permanent damage.

^{2.} S.C.L. = Single Carrier Level.

^{3.} Overall Rth depends on case mounting.

^{2.} Exceeding any of the above ratings may reduce MTTF below design goals.



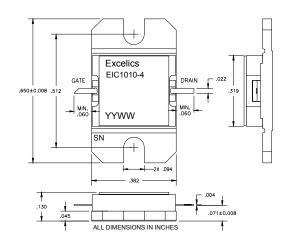
ISSUED 10/29/2008

10.0-10.70GHz 4-Watt Internally-Matched Power FET

PACKAGES OUTLINE

Dimensions in inches, Tolerance + .005 unless otherwise specified

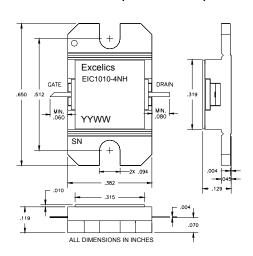
EIC1010-4 (Hermetic)





Caution! ESD sensitive device.

EIC1010-4NH (Non-Hermetic)





Caution! ESD sensitive device.

ORDERING INFORMATION

Part Number	Packages	Grade ¹	f _{Test} (GHz)	P _{1dB} (min)	IM ₃ (min) ²
EIC1010-4	Hermetic	Industrial	10.0-10.70GHz	35.5	-43
EIC1010-4NH	Non-Hermetic	Industrial	10.0-10.70GHz	35.5	-43

Notes:

- 1. Contact factory for military and hi-rel grades.
- 2. Exact test conditions are specified in "Electrical Characteristics" table.

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- 2. A critical component is any component of a life support device or system whose failure to perform can be reasonably expected to cause the failure of the life support device or system, or to affect its safety or effectiveness